

### JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

# **SMBG Plastic-Encapsulate Diodes**

### S3A THRU S3M General Purpose Rectifier Diodes

#### **Features**

• I<sub>F(AV)</sub> 3A

• VRRM 50V-1000V

• High surge current capability

• Polarity: Color band denotes cathode

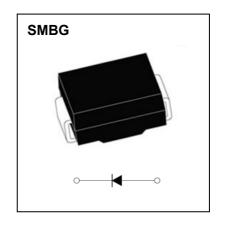
#### **Applications**

• Rectifier

#### Marking

• S3X

X: From A To M



### **Limiting Values(Absolute Maximum Rating)**

	Symbol	Unit		S3							
Item			Test Conditions	Α	В	D	G	J	K	М	
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	200	400	600	800	1000	
Maximum RMS Voltage	V <sub>RMS</sub>	V		35	70	140	280	420	560	700	
Average Forward Current	I <sub>F(AV)</sub>	А	60Hz Half-sine wave , Resistance load , T L =100 ℃				3.0				
Surge(Non-repetitive)Forward Current	I <sub>FSM</sub>	А	60Hz Half-sine wave, 1 cycle,Ta=25℃	100							
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	$^{\circ}\!$		-55 ~ +150							

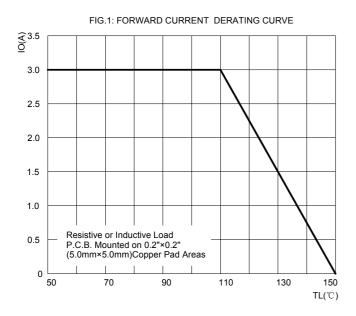
Electrical Characteristics (T=25°C Unless otherwise specified)

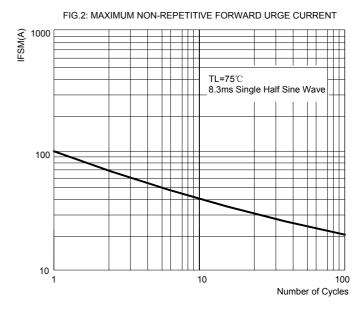
			Test Condition		<b>S3</b>							
ltem	Symbol	Unit			Α	В	D	G	J	K	M	
Peak Forward Voltage	$V_{F}$	V	I <sub>F</sub> =3.0A		1.1							
Darely Davisona Comment	I <sub>RRM1</sub>	μА	V <sub>RM</sub> =V <sub>RRM</sub>	T <sub>a</sub> =25℃				5.0				
Peak Reverse Current	I <sub>RRM2</sub>			T <sub>a</sub> =125℃				125				
Thermal	$R_{\theta_{J-A}}$	°C/W	Between junction and ambient			53						
Resistance(Typical)	$R_{\theta J-L}$	CTVV	Between junct	on and terminal				16				

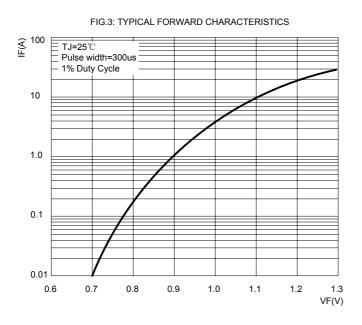
#### Notes

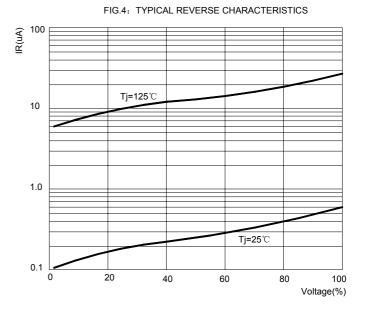
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.27" x 0.27" (7.0 mm x 7.0 mm) copper pad areas

## **Typical Characteristics**

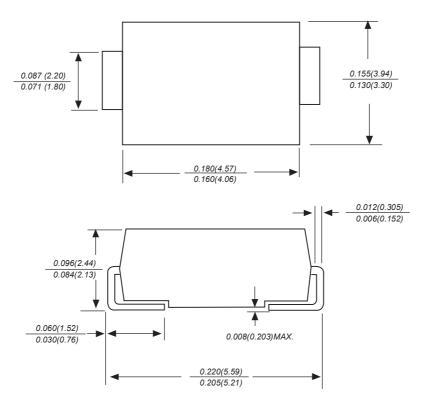






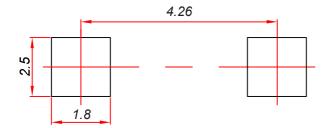


#### **SMBG** Package Outline Dimensions



Dimensions in inches and (millimeters)

### **SMBG** Suggested Pad Layout



#### Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### NOTICE

JSCJ reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

# Reel Taping Specifications For Surface Mount Devices-SMBG

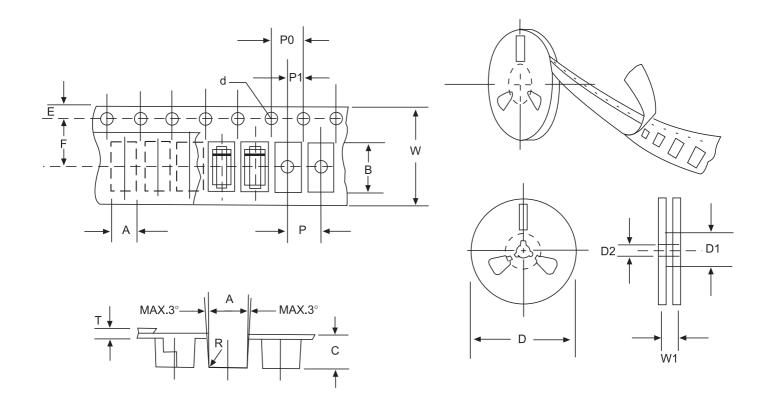


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMBG mm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	В	5.82±0.1(0.229±0.004)
Carrier depth	С	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.55±0.05 (0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0 (2.95±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	Р	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	Т	0.32±0.1 (0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.

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